

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT						
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT						
<b>CONVEYING PARTY DATA</b>							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Sang Min LEE</td> <td>12/19/2008</td> </tr> <tr> <td>Hyuck Jung CHOI</td> <td>12/19/2008</td> </tr> </tbody> </table>		Name	Execution Date	Sang Min LEE	12/19/2008	Hyuck Jung CHOI	12/19/2008
Name	Execution Date						
Sang Min LEE	12/19/2008						
Hyuck Jung CHOI	12/19/2008						
<b>RECEIVING PARTY DATA</b>							
<b>Name:</b>	SEOUL SEMICONDUCTOR CO., LTD.						
<b>Street Address:</b>	148-29 Gasan-dong, Geumcheon-gu, Gyeonggi-do						
<b>City:</b>	Seoul						
<b>State/Country:</b>	REPUBLIC OF KOREA						
<b>Postal Code:</b>	153-801						
<b>PROPERTY NUMBERS Total: 1</b>							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12306664</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12306664		
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Application Number:	12306664						
<b>CORRESPONDENCE DATA</b>							
<b>Fax Number:</b>	(703)288-5139						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
<b>Phone:</b>	703-288-5105						
<b>Email:</b>	patent@park-law.com						
<b>Correspondent Name:</b>	H.C. Park & Associates, PLC						
<b>Address Line 1:</b>	8500 Leesburg Pike, Suite 7500						
<b>Address Line 4:</b>	Vienna, VIRGINIA 22182						
<b>ATTORNEY DOCKET NUMBER:</b>	P2604US00						
<b>NAME OF SUBMITTER:</b>	Hae-Chan Park						
<b>Total Attachments: 2</b> source=P2604US00 Assignment#page1.tif source=P2604US00 Assignment#page2.tif							

OP \$40.00 12306664



### ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled **LIGHT EMITTING DEVICE** ("Application");

upon which United States Letters Patent, Patent Number \_\_\_\_\_, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

**Seoul Semiconductor Co. Ltd.**  
148-29 Gasan-dong, Geumcheon-gu  
Gyeonggi-do  
153-801 Seoul  
South Korea

**Seoul Semiconductor Co. Ltd.** herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to



carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Sang Min LEE

Address: 304-1701 Daewoo APT., Eunhaeng-dong  
Gyeonggi-do  
429-060 Siheung-si  
Republic of Korea

First Inventor's Signature:

Date:

Dec. 19, 2008

Second Inventor's Name: Hyuck Jung CHOI

Address: 406-1401, Daelim 1cha APT.  
642, Sindorim-dong, Guro-gu  
152-888 Seoul  
Republic of Korea

Second Inventor's Signature:

Date:

December 19, 2008